

Applicant: Chi-Wei Huang, et al.
Serial No.: 10/761,881
Attorney Docket No.: 67,200-1225

IN THE CLAIMS

Please cancel claims 13-16.

Please amend claims 1-9 as follows.

1. (Currently amended) An insert ring assembly for a process chamber, comprising:

an insert ring having a ring body defining a central ring opening; and an annular step having an upper step surface provided on said ring body and spaced-apart from said central ring opening; and

a shadow ring encircling said insert ring and extending beyond said upper step surface of said insert ring.

2. (Currently amended) The insert ring assembly of claim 1 wherein said ring body comprises silicon.

3. (Currently amended) The insert ring assembly of claim 1 wherein said ring body has a ring body thickness of about 3.5 mm.

4. (Currently amended) The insert ring assembly of claim 3 wherein said ring body comprises silicon.

5. (Currently amended) The insert ring assembly of claim 1 wherein said step has a step thickness of about 1.5 mm.

6. (Currently amended) The insert ring assembly of claim 1 wherein said process chamber comprises etching process chamber.

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7. (Currently amended) The insert ring assembly of claim 5 wherein said ring body has a ring body thickness of about 3.5 mm.

8. (Currently amended) The insert ring assembly of claim 7 wherein said ring body comprises silicon.

9. (Currently amended) An insert ring assembly for a process chamber, comprising:

a wafer support for supporting a wafer;

an insert ring encircling said wafer support, said insert ring comprising a ring body defining a central ring opening and an annular step having an upper step surface provided on said ring body and spaced-apart from said central ring opening; and

a generally perpendicular flow space defined between said insert ring and said wafer support; and

a shadow ring encircling said insert ring and extending beyond said upper step surface of said insert ring.

10. (Original) The insert ring assembly of claim 9 wherein said ring body comprises silicon.

11. (Original) The insert ring assembly of claim 9 wherein said ring body has a ring body thickness of about 3.5 mm and said step has a step thickness of about 1.5 mm.

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12. (Original) The insert ring of claim 9 wherein said process chamber comprises etching process chamber.

13-16 (Canceled)

17. (Withdrawn) A method of preventing formation of polymer residues on an inner surface of an insert ring encircling a substrate support during processing of a substrate on the substrate support, comprising the step of:

providing a generally perpendicular flow space between said insert ring and said substrate support by providing a generally step-shaped cross-sectional profile to said insert ring.

18. (Withdrawn) The method of claim 17 wherein said insert ring comprises a ring body defining a central ring opening and an annular step provided on said ring body and spaced-apart from said central ring opening.

19. (Withdrawn) The method of claim 17 wherein said insert ring comprises quartz.

20. (Withdrawn) The method of claim 19 wherein said insert ring comprises a ring body defining a central ring opening and an annular step provided on said ring body and spaced-apart from said central ring opening.